

Title (en)
COPPER POROUS BODY, COPPER POROUS COMPOSITE MEMBER, METHOD FOR PRODUCING COPPER POROUS BODY, AND METHOD FOR PRODUCING COPPER POROUS COMPOSITE MEMBER

Title (de)
PORÖSER KUPFERKÖRPER, PORÖSES KUPFERVERBUNDELEMENT, VERFAHREN ZUR HERSTELLUNG DES PORÖSEN KUPFERKÖRPERS UND VERFAHREN ZUR HERSTELLUNG DES PORÖSEN KUPFERVERBUNDELEMENTS

Title (fr)
CORPS POREUX EN CUIVRE, ÉLÉMENT COMPOSITE POREUX EN CUIVRE, PROCÉDÉ DE PRODUCTION DE CORPS POREUX EN CUIVRE ET PROCÉDÉ DE PRODUCTION D'ÉLÉMENT COMPOSITE POREUX EN CUIVRE

Publication
EP 3572169 A4 20200708 (EN)

Application
EP 18741976 A 20180118

Priority
• JP 2017006749 A 20170118
• JP 2018001370 W 20180118

Abstract (en)
[origin: EP3572169A1] This porous copper body includes: a skeleton which is formed of a sintered body of a plurality of copper fibers and has a three-dimensional network structure, wherein the copper fibers forming the skeleton consist of copper or a copper alloy, and the copper fibers have a diameter R in a range of 0.01 mm to 1.0 mm, a ratio L/R of a length L to the diameter R in a range of 4 to 200, and a circularity of a cross section orthogonal to a length direction in a range of 0.2 to 0.9, and the porous copper body has a porosity of 50% to 95%.

IPC 8 full level
B22F 3/11 (2006.01); **B22F 3/00** (2006.01); **B22F 7/08** (2006.01); **C22C 1/00** (2006.01); **C22C 1/08** (2006.01); **B22F 1/062** (2022.01)

CPC (source: EP KR US)
B22F 3/002 (2013.01 - EP US); **B22F 3/11** (2013.01 - EP KR); **B22F 3/1103** (2013.01 - US); **B22F 7/002** (2013.01 - KR);
B22F 7/08 (2013.01 - EP KR US); **C22C 1/00** (2013.01 - EP); **C22C 1/08** (2013.01 - EP KR US); **B22F 1/062** (2022.01 - EP KR US);
B22F 2301/10 (2013.01 - KR US); **Y10T 428/12042** (2015.01 - US)

Citation (search report)
• [I] JP 2017002379 A 20170105 - MITSUBISHI MATERIALS CORP
• See references of WO 2018135575A1

Cited by
EP4000710A1; WO2022106606A1

Designated contracting state (EPC)
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DOCDB simple family (publication)
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KR 20190108103 A 20190923; TW 201842200 A 20181201; US 2019381568 A1 20191219; WO 2018135575 A1 20180726

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